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TE Internal #: 3-1658462-2 PCB Mount Receptacle, Vertical, Board-to-Board, 56 Position, .8mm [.031in] Centerline, Fully Shrouded, Select Gold, Printed Circuit Board

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Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 56

Centerline (Pitch): .8 mm [.031 in]

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Receptacle

Board-to-Board

Fully Shrouded



Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Rows	2
Stackable	No
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	56
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Dielectric Withstanding Voltage (Max)	675 VAC
Insulation Resistance	2 MΩ
Impedance	100 Ω
Operating Voltage	125 VAC
Body Features	

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Assembly Process Feature Material	Polyimide Film
Contact Features	
PCB Contact Termination Area Plating Material Thickness	.76 μm[29.9212 μin]
Mating Tab Width	.38 mm[.015 in]
Mating Tab Thickness	.2 mm[.008 in]
Contact Shape & Form	Single Beam
PCB Contact Termination Area Plating Material	Gold
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Select Gold
Contact Mating Area Plating Material Thickness	.76 μm[29.9212 μin]
Contact Type	Socket
Contact Current Rating (Max)	1.25 A, 9.5 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.15 mm[.006 in]
Rectangular Termination Post & Tail Width	1.77 mm[.07 in]
Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
PCB Mount Alignment Type	Locating Posts
Mating Retention	With
Mating Alignment	Without
PCB Mount Retention	With
PCB Mount Alignment	With
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	.8 mm[.031 in]
Housing Color	Black
Housing Material	LCP (Liquid Crystal Polymer)
Dimensions	
Connector Height	3.05 mm[.12 in]
Row-to-Row Spacing	3.47 mm[.136 in]
Stack Height	5 mm, 8 mm, 11 mm, 16 mm, 19 mm, 22 mm, 25 mm, 30 mm[1.181 in]
PCB Thickness (Recommended)	.06 mm[.8 in]

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Usage Conditions Operating Temperature Range -65 - 125 °C[-85 - 257 °F] **Operation/Application** Assembly Process Feature Pick and Place Cover Power & Signal **Circuit Application Industry Standards** UL Flammability Rating UL 94V-0 Packaging Features Packaging Quantity 56 Packaging Method Box & Tray, Tray Other Use of stand offs recommended. Contact Comment Product Engineering for recommendations.

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU

Not Yet Reviewed

EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JUN 2012 (84) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Reflow solder capable to 260°C

Product Compliance Disclaimer

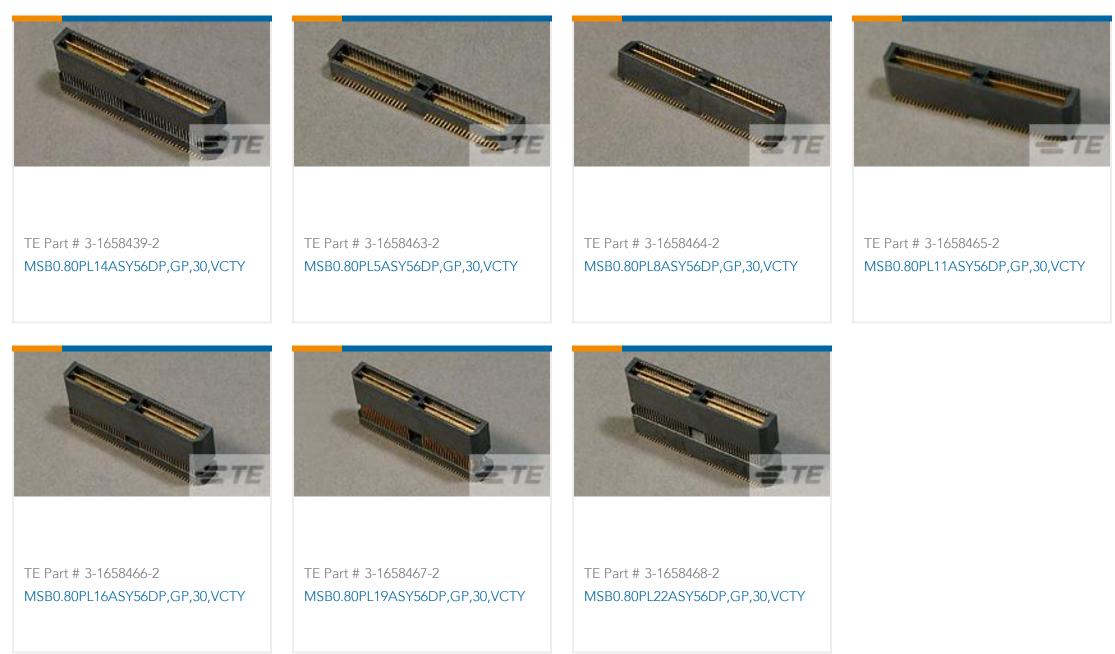
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in

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articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

Compatible Parts

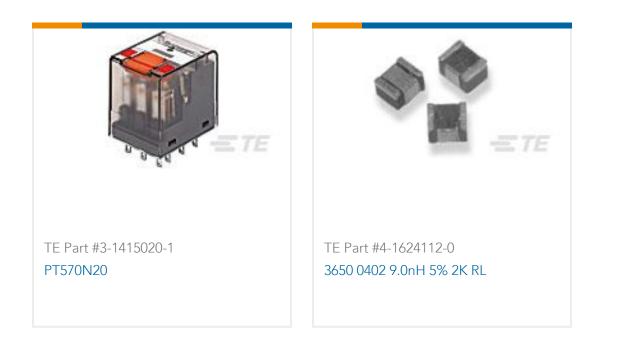


Customers Also Bought



PCB Mount Receptacle, Vertical, Board-to-Board, 56 Position, .8mm [.031in] Centerline, Fully Shrouded, Select Gold, Printed Circuit Board





Documents

Product Drawings MSB0.80RC-ASY56DP,GP,30,VCTY

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_3-1658462-2_L_c-3-1658462-2-l.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_3-1658462-2_L_c-3-1658462-2-l.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_3-1658462-2_L_c-3-1658462-2-l.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English